JOCDE0CB-M5

Rev.A.1.0

DESCRIPTION:

The products are gate driver opto-couplers in the SOP5 package. The device consists of an infrared LED optically coupled to an integrated high-gain, high-speed photodetector IC chip. It provides guaranteed performance and specifications at temperature up to 110 . It is physically smaller and compliant with international safety standards for reinforced insulation. It thus provides a smaller footprint solution for applications that require safety standard certification. An internal noise shield provides a guaranteed common-mode transient immunity of ±35 kV/μs. It is ideal for small class IGBT and power MOSFET gate drive. The products are widely used in industrial inverters, IGBT gate drivers, MOSFET gate drivers, induction cooktop and home appliances.

MAIN FEATURES

0.1A maximum peak output current
High isolation 3750 VRMS
Buffer logic type
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

Truth Table

Input	LED	Output
H	ON	L
L	OFF	H

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter	Symbol	Value	Uni	ώmn

	Power Dissipation	P_D	100	mW
Detector	Output Voltage	V_O	30	V
	Supply Voltage	V_{CC}	30	V
	Power Dissipation	P_C	400	mW
Isolation Voltage		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Total Power Dissipation		P_{tot}	500	mW
Soldering Temperature		T_{sol}	260	

NOTE1: μ

NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.35	1.6	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
	Terminal Capacitance	C_t	V=0,f=1MHz	-	60	-	pF
Output	Peak High-level Output Current	I_{OPH}	V_{CC}=5.5V, V_O=GND	-	-350	-150	mA
			V_{CC}=20V, V_O=GND	-	-350	-160	mA
	Peak Low-level Output Current	I_{OPL}	I_F=5mA, V_{CC}=V_O=5.5V	150	270	-	mA
			I_F=5mA, V_{CC}=V_O=20V	160	300	-	mA
	High Level Supply Current	I_{CCH}	V_{CC}=5.5V	-	2.1	3	mA
			V_{CC}=30V	-	2.35	3	mA
	Low Level Supply Current	I_{CCL}	I_F=5mA, V_{CC}=5.5V	-	2.1	3	mA
			I_F=5mA, V_{CC}=30V	-	2.35	3	mA
	High Level Output Voltage	V_{OH}	I_O=-3.5mA	V_{CC}-0.2	V_{CC}-0.03	-	V
			I_O=-6.5mA	V_{CC}-0.4	V_{CC}-0.05	-	V
	Low Level Output Voltage	V_{OL}	I_F=5mA, V_F=0.8V, I_O=3.5mA	-	0.026	0.2	V

Recommended Operating Conditions

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	$I_{F(ON)}$	7	-	15	mA
Input Off-state Voltage	$V_{F(OFF)}$	0	-	0.8	V
Supply Voltage	V_{CC}	4.5	-	30	V

Note1

Note2

Note3

Note4

ORDERING INFORMATION



OC D E 0 C B -M5 / X

Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

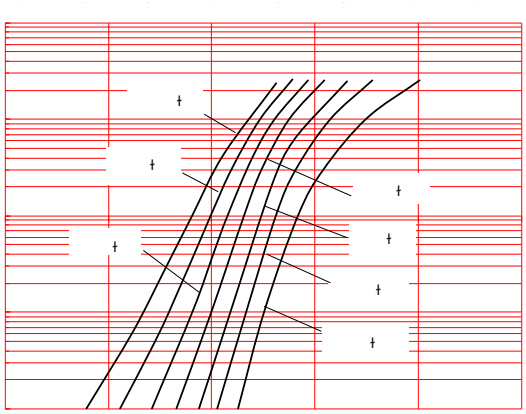


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

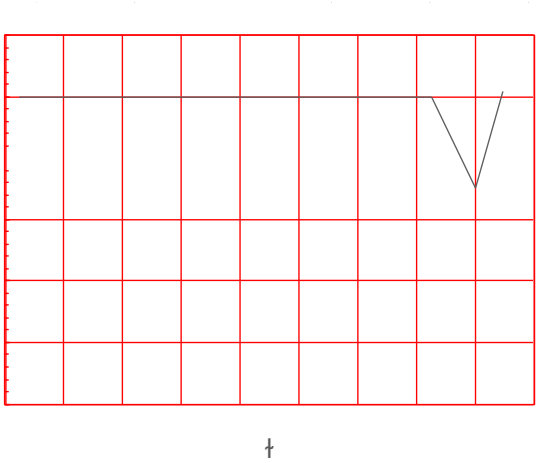


FIG.3: Collector Power Dissiption vs. Ambient Temperature

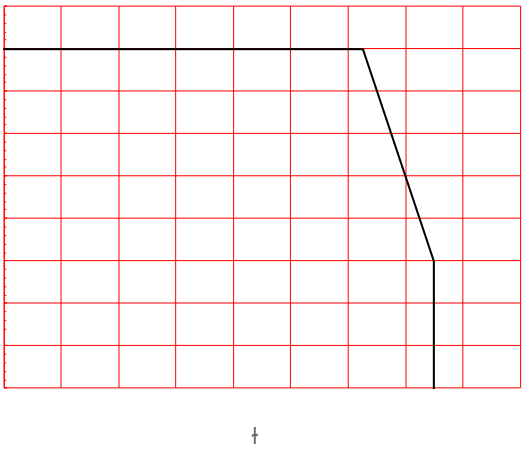


FIG.4: Threshold Input Current vs. Ambient Temperature

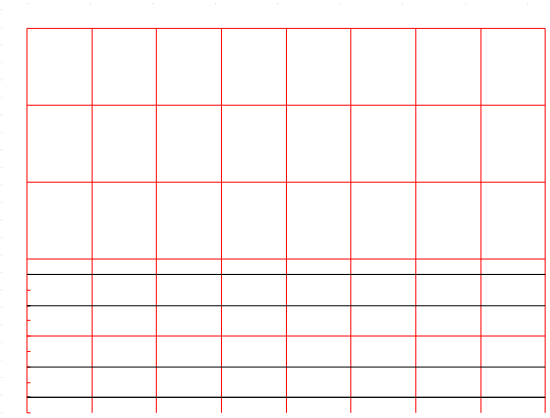
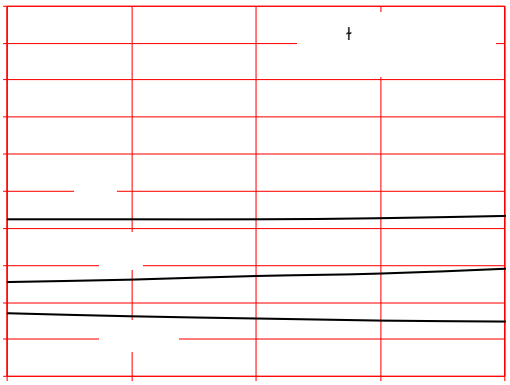


FIG.13: Propagation Delay Time,Pulse Width Distortion vs. Supply Voltage



Test Circuits

FIG.14: Switching Time Test Circuit and Waveform

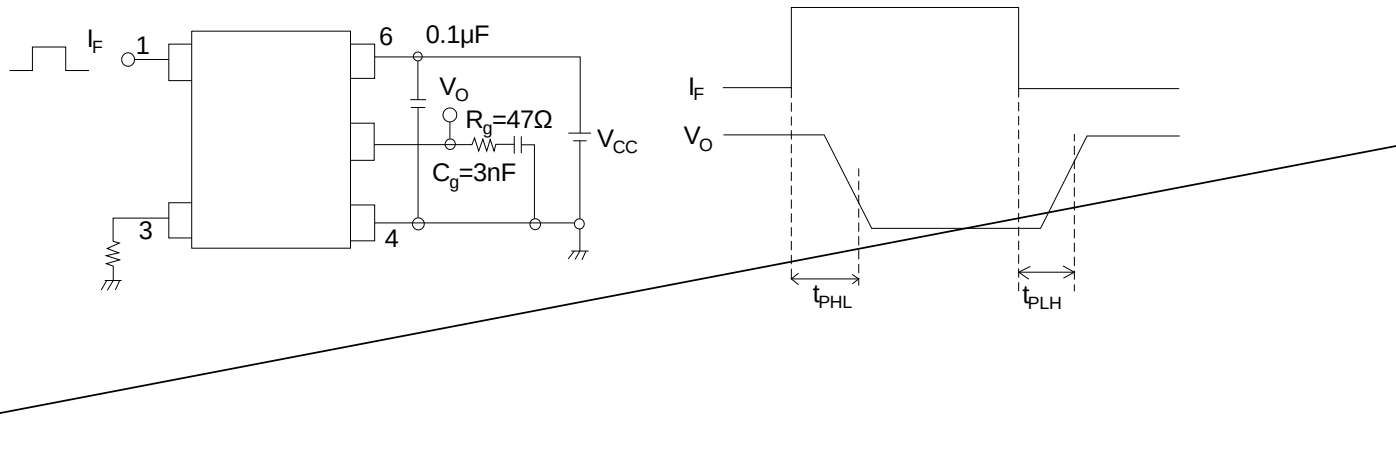


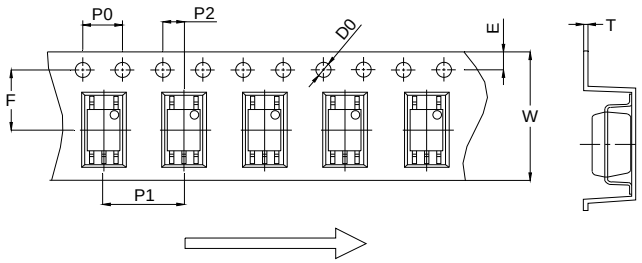
FIG.15:

Package Dimension (Unit: mm)

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A						
B						
C						
D						
E						
F	0.34			0.013		
G						
H						
I	2.00			0.079		
J			0.55	0.010		

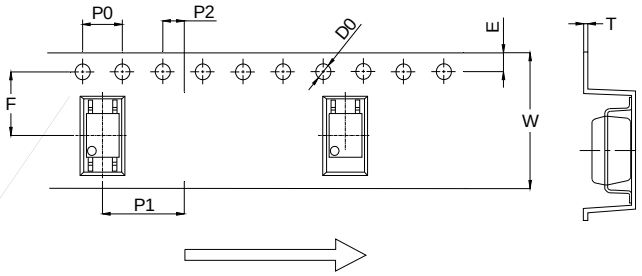
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None



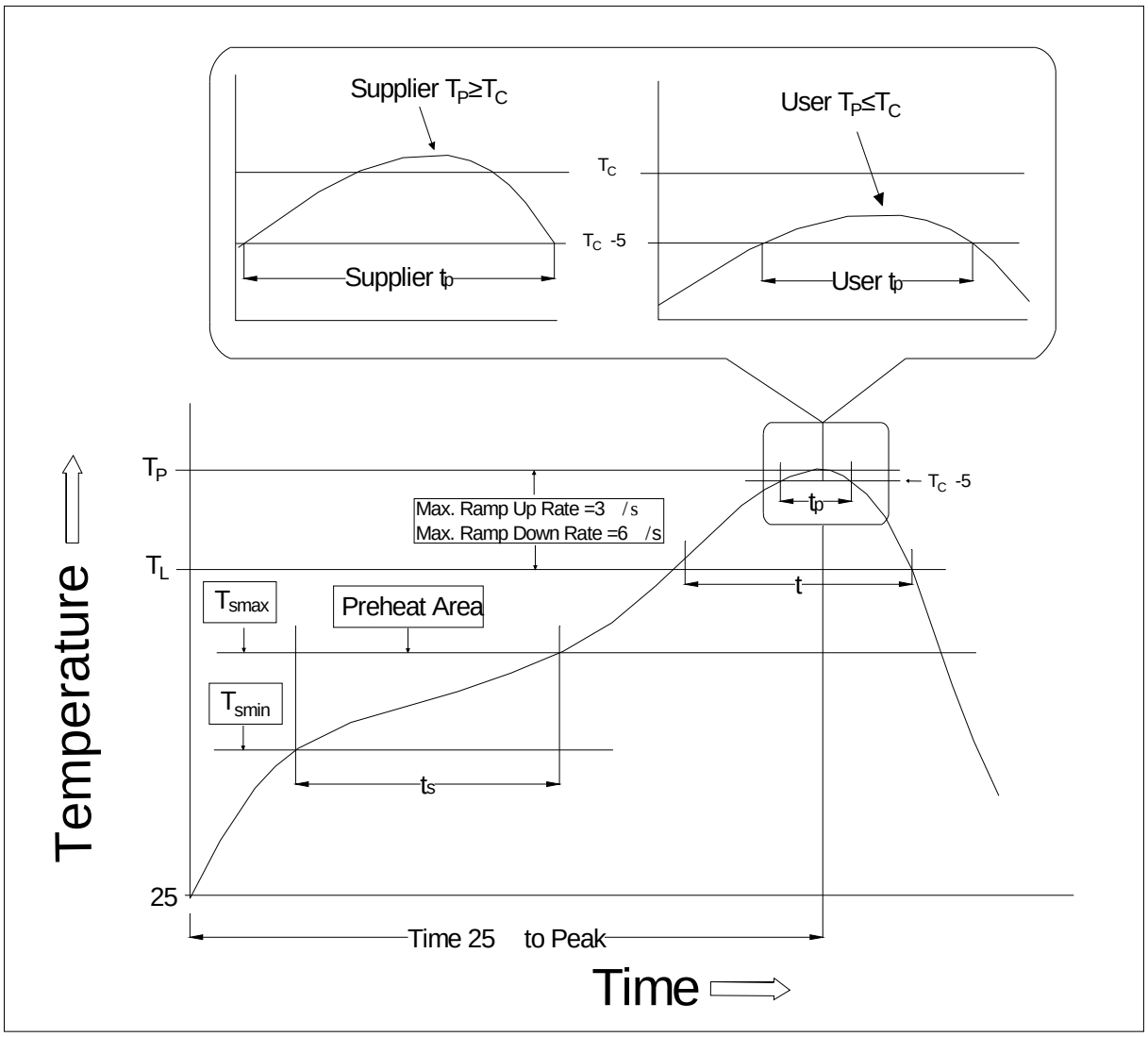
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

Option R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0						
P0						
P1						
P2						
E						
F						
T						
W						

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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